

IRF7805

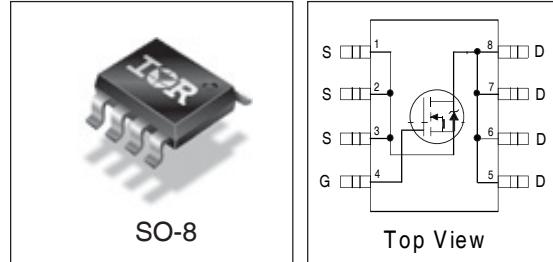
HEXFET® Chip-Set for DC-DC Converters

- N Channel Application Specific MOSFETs
- Ideal for Mobile DC-DC Converters
- Low Conduction Losses
- Low Switching Losses

Description

This new device employs advanced HEXFET Power MOSFET technology to achieve an unprecedented balance of on-resistance and gate charge. The reduced conduction and switching losses make this device ideal for high efficiency DC-DC Converters that power the latest generation of mobile microprocessors.

The IRF7805 offers maximum efficiency for mobile CPU core DC-DC converters.



Device Features

	IRF7805
V _{DS}	30V
R _{DS(on)}	11mΩ
Q _g	31nC
Q _{sw}	11.5nC
Q _{oss}	36nC

Absolute Maximum Ratings

	Parameter	Max.	Units
V _{DS}	Drain-to-Source Voltage	30	V
V _{GS}	Gate-to-Source Voltage	± 12	
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V ③	13	A
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V ③	10	
I _{DM}	Pulsed Drain Current ①	100	
P _D @ T _A = 25°C	Power Dissipation ③	2.5	W
P _D @ T _A = 70°C	Power Dissipation ③	1.6	
	Linear Derating Factor	0.02	W/°C
T _J	Operating Junction and	-55 to + 150	°C
T _{STG}	Storage Temperature Range		

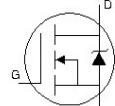
Thermal Resistance

	Parameter	Typ.	Max.	Units
R _{0JL}	Junction-to-Drain Lead ⑤	—	20	°C/W
R _{0JA}	Junction-to-Ambient ③⑤	—	50	

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage ^⑤	30	—	—	V	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$
$R_{\text{DS(on)}}$	Static Drain-to-Source On-Resistance ^⑥	—	9.2	11	$\text{m}\Omega$	$V_{\text{GS}} = 4.5\text{V}$, $I_D = 7.0\text{A}$ ②
$V_{\text{GS(th)}}$	Gate Threshold Voltage ⑥	1.0	—	3.0	V	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	70	μA	$V_{\text{DS}} = 30\text{V}$, $V_{\text{GS}} = 0\text{V}$
		—	—	10		$V_{\text{DS}} = 24\text{V}$, $V_{\text{GS}} = 0\text{V}$
		—	—	150		$V_{\text{DS}} = 24\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_J = 100^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}} = 12\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = -12\text{V}$
Q_g	Total Gate Charge ⑥	—	22	31	nC	$V_{\text{GS}} = 5.0\text{V}$
$Q_{\text{gs}1}$	Pre-Vth Gate-to-Source Charge	—	3.7	—		$V_{\text{DS}} = 16\text{V}$
$Q_{\text{gs}2}$	Post-Vth Gate-to-Source Charge	—	1.4	—		$I_D = 7.0\text{A}$
Q_{gd}	Gate-to-Drain Charge	—	6.8	—		
Q_{sw}	Switch Charge ($Q_{\text{gs}2} + Q_{\text{gd}}$) ⑥	—	8.2	11.5		
Q_{oss}	Output Charge ⑥	—	3.0	3.6	nC	$V_{\text{DS}} = 16\text{V}$, $V_{\text{GS}} = 0\text{V}$
R_G	Gate Resistance	0.5	—	1.7	Ω	
$t_{\text{d(on)}}$	Turn-On Delay Time	—	16	—	ns	$V_{\text{DD}} = 16\text{V}$, $V_{\text{GS}} = 4.5\text{V}$ ③
t_r	Rise Time	—	20	—		$I_D = 7.0\text{A}$
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	38	—		$R_G = 2\Omega$
t_f	Fall Time	—	16	—		Resistive Load

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode) ①	—	—	2.5	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode)	—	—	106		
V_{SD}	Diode Forward Voltage ⑥	—	—	1.2	V	$T_J = 25^\circ\text{C}$, $I_S = 7.0\text{A}$, $V_{\text{GS}} = 0\text{V}$
Q_{rr}	Reverse Recovery Charge ④	—	88	—	ns	$di/dt = 700\text{A}/\mu\text{s}$ $V_{\text{DS}} = 16\text{V}$, $V_{\text{GS}} = 0\text{V}$, $I_S = 7.0\text{A}$
$Q_{\text{rr(s)}}$	Reverse Recovery Charge (with Parallel Schottky) ④	—	55	—	nC	$di/dt = 700\text{A}/\mu\text{s}$ (with 10BQ040) $V_{\text{DS}} = 16\text{V}$, $V_{\text{GS}} = 0\text{V}$, $I_S = 7.0\text{A}$

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width $\leq 300 \mu\text{s}$; duty cycle $\leq 2\%$.
- ③ When mounted on 1 inch square copper board, $t < 10$ sec.
- ④ Typ = measured - Q_{oss}
- ⑤ R_{g} is measured at T_J of approximately 90°C .
- ⑥ Devices are 100% tested to these parameters.

Typical Characteristics

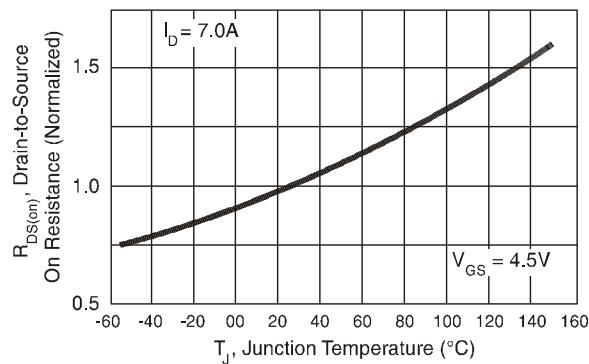


Fig 1. Normalized On-Resistance vs. Temperature

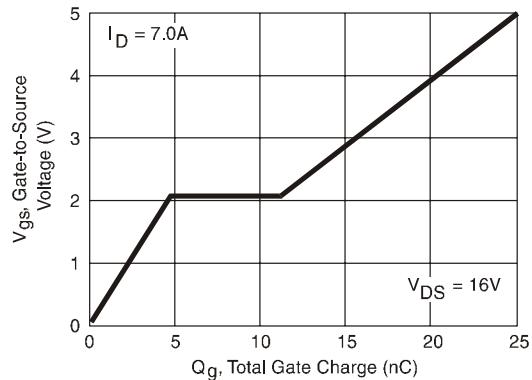


Fig 2. Typical Gate Charge vs. Gate-to-Source Voltage

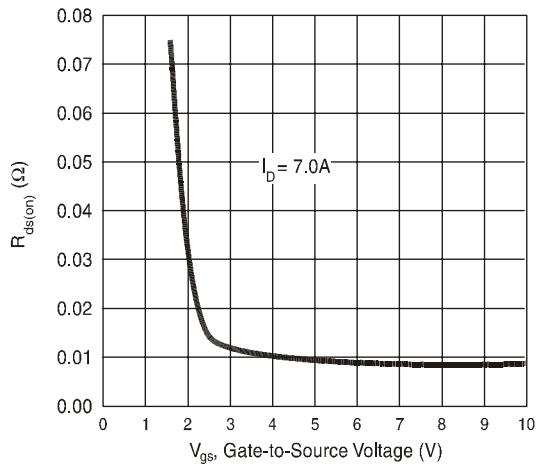


Fig 3. Typical R_ds(on) vs. Gate-to-Source Voltage

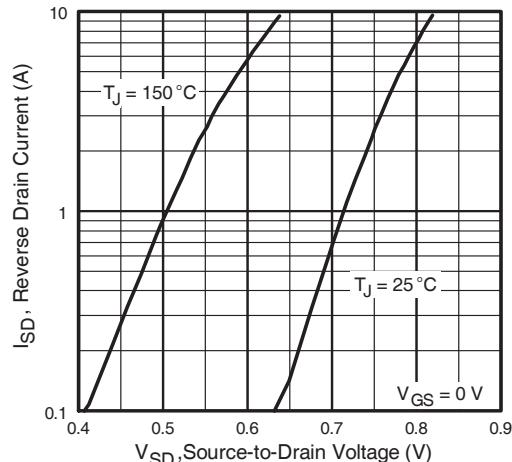


Fig 4. Typical Source-Drain Diode Forward Voltage

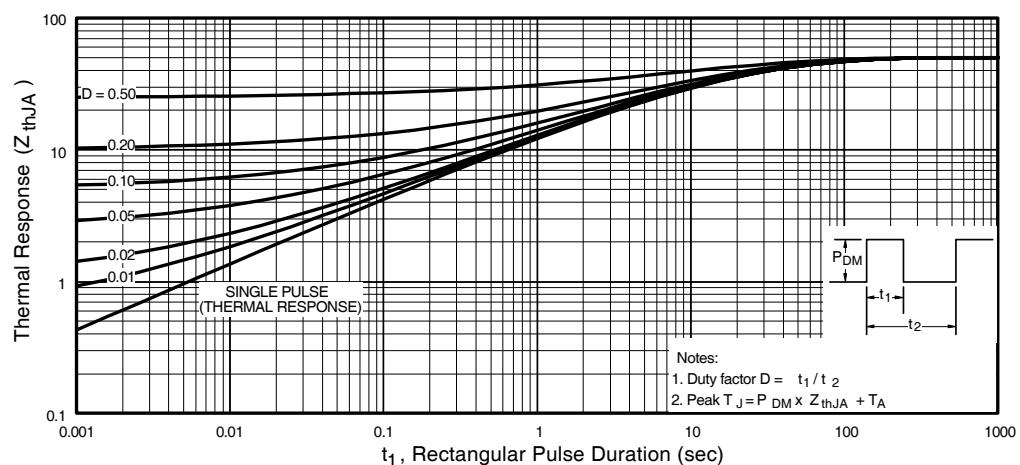
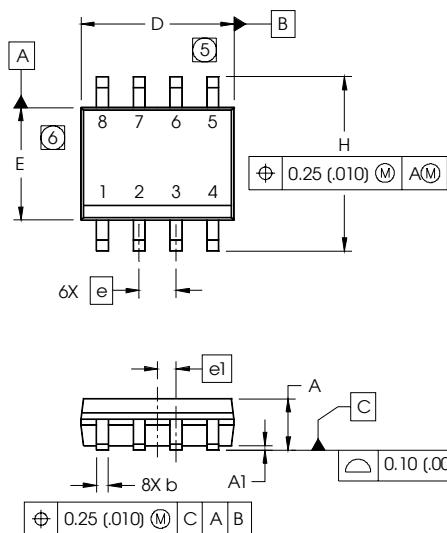


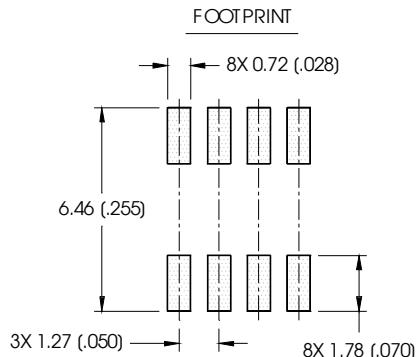
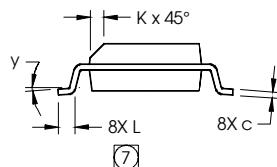
Figure 5. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

SO-8 Package Details

Dimensions are shown in millimeters (inches)



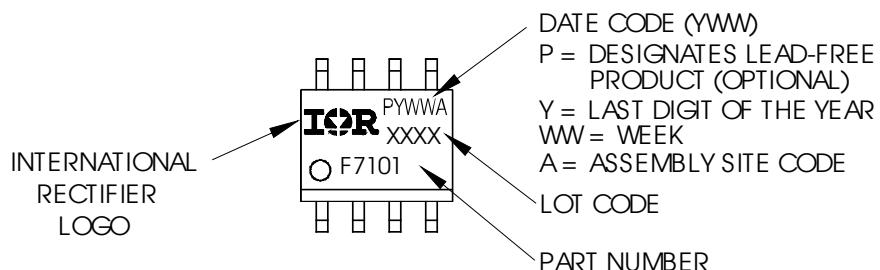
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050	BASIC	1.27	BASIC
e1	.025	BASIC	0.635	BASIC
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



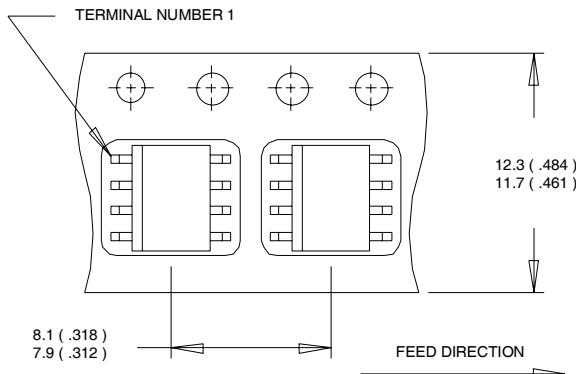
- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
 2. CONTROLLING DIMENSION: MILLIMETER
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
 - ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS.
MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
 - ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS.
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
 - ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO
A SUBSTRATE.

SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)

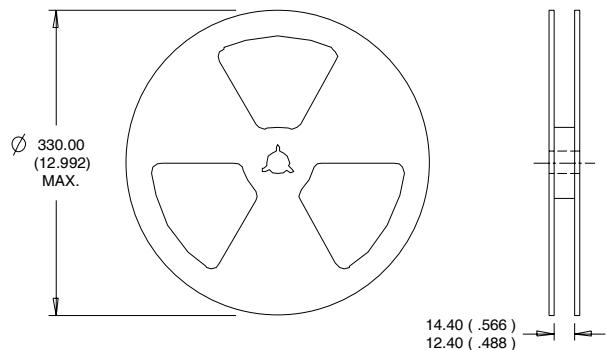


SO-8 Tape and Reel



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

International
IR Rectifier

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